

ABSTRACT

A semiconductor package includes a semiconductor chip connected to lead frames by wires and outer leads protruding from the semiconductor package. At this time, the outer leads are connected to the lead frames and grooves into which the outer leads are inserted into are provided in the semiconductor package, wherein the grooves are connected the lead frames. In mounting a first and a second semiconductor package, the outer leads of the first semiconductor package are inserted into the grooves of the second semiconductor package.